BAV99WT1, SBAV99WT1G, BAV99RWT1, SBAV99RWT1G

Dual Series Switching Diodes

The BAV99WT1 is a smaller package, equivalent to the BAV99LT1.

Features

- These Devices are Pb-Free and are RoHS Compliant
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable

Suggested Applications

- ESD Protection
- Polarity Reversal Protection
- Data Line Protection
- Inductive Load Protection
- Steering Logic

MAXIMUM RATINGS (Each Diode)

Rating	Symbol	Value	Unit
Reverse Voltage	V _R	100	Vdc
Forward Current	ΙF	215	mAdc
Peak Forward Surge Current	I _{FM(surge)}	500	mAdc
Repetitive Peak Reverse Voltage	V _{RRM}	70	V
Average Rectified Forward Current (Note 1) (averaged over any 20 ms period)	I _{F(AV)}	715	mA
Repetitive Peak Forward Current	I _{FRM}	450	mA
Non-Repetitive Peak Forward Current $t = 1.0 \mu s$ $t = 1.0 ms$ $t = 1.0 s$	I _{FSM}	2.0 1.0 0.5	Α

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.

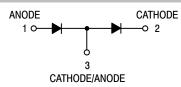


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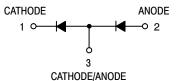
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SC-70 CASE 419

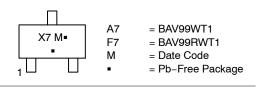


BAV99WT1 SC-70, CASE 419, STYLE 9



BAV99RWT1 SC-70, CASE 419, STYLE 10

MARKING DIAGRAM



ORDERING INFORMATION

Device	Package	Shipping [†]
BAV99WT1G	SC-70 (Pb-Free)	3,000 / Tape & Reel
SBAV99WT1G	SC-70 (Pb-Free)	3,000 / Tape & Reel
BAV99RWT1G	SC-70 (Pb-Free)	3,000 / Tape & Reel
SBAV99RWT1G	SC-70 (Pb-Free)	3,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

BAV99WT1, SBAV99WT1G, BAV99RWT1, SBAV99RWT1G

THERMAL CHARACTERISTICS

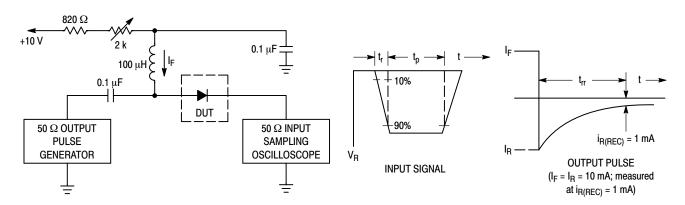
Characteristic	Symbol	Max	Unit
Total Device Dissipation FR–5 Board, (Note 1) T _A = 25°C Derate above 25°C	P _D	200 1.6	mW mW/°C
Thermal Resistance Junction-to-Ambient	$R_{ hetaJA}$	625	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) T _A = 25°C Derate above 25°C	P _D	300 2.4	mW mW/°C
Thermal Resistance Junction-to-Ambient	$R_{ hetaJA}$	417	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-65 to +150	°C

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted) (Each Diode)

Characteristic	Symbol	Min	Max	Unit		
OFF CHARACTERISTICS						
Reverse Breakdown Voltage (I _(BR) = 100 μA)	V _(BR)	100	-	Vdc		
Reverse Voltage Leakage Current $(V_R = 100 \text{ Vdc})$ $(V_R = 25 \text{ Vdc}, T_J = 150^{\circ}\text{C})$ $(V_R = 70 \text{ Vdc}, T_J = 150^{\circ}\text{C})$	I _R	- - -	2.5 30 50	μAdc		
Diode Capacitance (V _R = 0, f = 1.0 MHz)	C _D	_	1.5	pF		
Forward Voltage $ \begin{aligned} &(I_F = 1.0 \text{ mAdc}) \\ &(I_F = 10 \text{ mAdc}) \\ &(I_F = 10 \text{ mAdc}) \\ &(I_F = 50 \text{ mAdc}) \\ &(I_F = 150 \text{ mAdc}) \end{aligned} $	V _F	- - - -	715 855 1000 1250	mVdc		
Reverse Recovery Time (I _F = I _R = 10 mAdc, i _{R(REC)} = 1.0 mAdc) (Figure 1) R _L = 100 Ω	t _{rr}	_	6.0	ns		
Forward Recovery Voltage (I _F = 10 mA, t _r = 20 ns)	V _{FR}	_	1.75	V		

^{1.} FR-5 = $1.0 \times 0.75 \times 0.062$ in.

^{2.} Alumina = $0.4 \times 0.3 \times 0.024$ in. 99.5% alumina.



Notes: (a) A 2.0 $k\Omega$ variable resistor adjusted for a Forward Current (IF) of 10 mA.

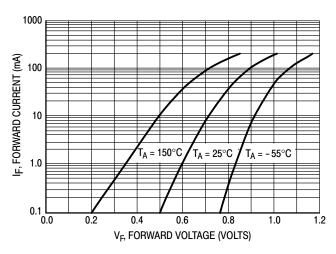
(b) Input pulse is adjusted so $I_{\mbox{\scriptsize R(peak)}}$ is equal to 10 mA.

(c) t_p » t_{rr}

Figure 1. Recovery Time Equivalent Test Circuit

BAV99WT1, SBAV99WT1G, BAV99RWT1, SBAV99RWT1G

CURVES APPLICABLE TO EACH DIODE



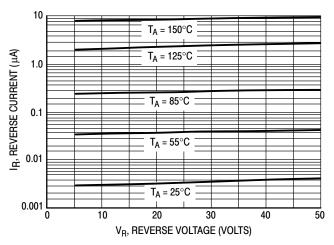


Figure 2. Forward Voltage

Figure 3. Leakage Current

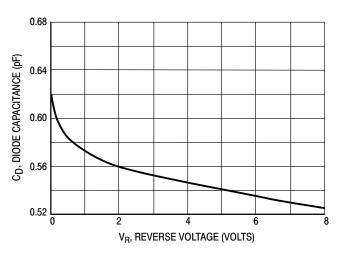
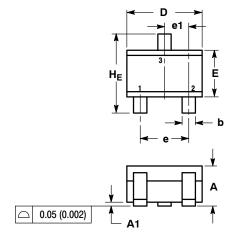


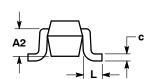
Figure 4. Capacitance

BAV99WT1, SBAV99WT1G, BAV99RWT1, SBAV99RWT1G

PACKAGE DIMENSIONS

SC-70 (SOT-323) CASE 419-04 ISSUE N





NOTES:

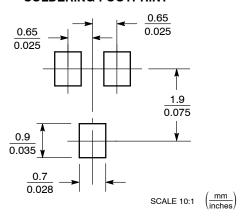
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	MOM	MAX
Α	0.80	0.90	1.00	0.032	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A2	0.70 REF			0.028 REF		
b	0.30	0.35	0.40	0.012	0.014	0.016
c	0.10	0.18	0.25	0.004	0.007	0.010
D	1.80	2.10	2.20	0.071	0.083	0.087
E	1.15	1.24	1.35	0.045	0.049	0.053
е	1.20	1.30	1.40	0.047	0.051	0.055
e1	0.65 BSC			0.026 BSC		
L	0.20	0.38	0.56	0.008	0.015	0.022
HE	2 00	2 10	2 40	0.079	0.083	0.095

STYLE 9: PIN 1. ANODE

CATHODE CATHODE-ANODE STYLE 10: PIN 1. CATHODE ANODE 3 ANODE-CATHODE

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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